

ABSTRACT

A contact pin unit includes: contact pins each of which has one end that comes into contact with an IC package and an other end that comes into contact with a circuit board; and contact pin frames in each of which a plurality of grooves are formed in parallel along a surface of a plate body, the contact pin frames being stacked in a plate thickness direction in a state where the contact pins are arranged in the grooves with the one end and the other end of each of the contact pins projecting outward from the plate body. A small projection that crushes when the stacked contact pin frames are compressed in a stack direction is formed on part of a front surface of the contact pin frames in a stack state which abut each other in the stack direction.